ACE2020M
N-Channel 200-V MOSFET

Description

ACE2020M uses advanced trench technology to provide excellent $R_{DS(ON)}$.

This device particularly suits for low voltage application such as power management of desktop computer or notebook computer power management, DC/DC converter.

Features

- Low $r_{DS(on)}$ trench technology
- Low thermal impedance
- Fast switching speed

Applications:

- White LED boost converters
- Automotive Systems
- Industrial DC/DC Conversion Circuits

Absolute Maximum Ratings

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	200	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_C=25℃	I_D	12	A
Pulsed Drain Current [b]		I_{DM}	50	A
Continuous Source Current (Diode Conduction) [a]		I_S	47	A
Power Dissipation	T_C=25℃	P_D	50	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 175	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Maximum	Unit
Maximum Junction-to-Ambient [a]	$R_{\theta JA}$	40	℃/W
Maximum Junction-to-Case	$R_{\theta JC}$	3	

Notes

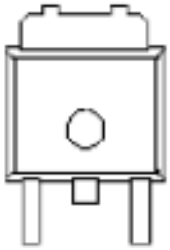
a. Surface Mounted on 1” x 1” FR4 Board, drain pad using 2 oz copper, value dependent on PC board thermal characteristics.

b. Pulse width limited by maximum junction temperature.

ACE2020M
N-Channel 200-V MOSFET

Packaging Type

TO-252



G D S

Ordering information

ACE2020M YM + H

- Halogen - free
- Pb - free
- YM : TO252

Electrical Characteristics

T_A=25°C, unless otherwise specified.

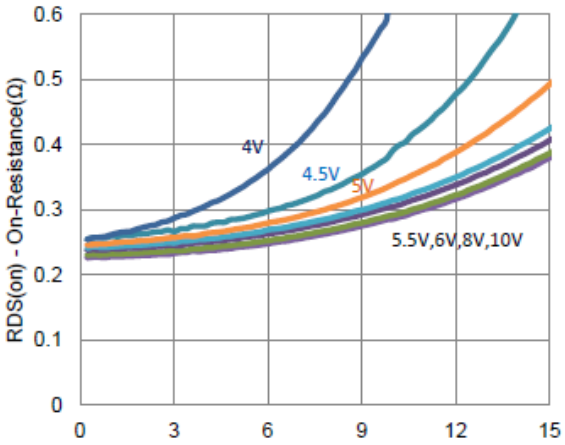
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 uA	1			V
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 160 V, V_{GS} = 0 V			1	uA
		V_{DS} = 160 V, V_{GS} = 0 V, T_J = 55°C			25	
On-State Drain Current	$I_{D(on)}$	V_{DS} = 5 V, V_{GS} = 10 V	24			A
Drain-Source On-Resistance	$r_{DS(on)}$	V_{GS} = 10 V, I_D = 9.6 A			260	mΩ
		V_{GS} = 5.5 V, I_D = 8.3 A			300	
Forward Transconductance	g_{fs}	V_{DS} = 15 V, I_D = 9.6 A		4.4		S
Diode Forward Voltage	V_{SD}	I_S = 23 A, V_{GS} = 0 V		0.95		V
Dynamic						
Total Gate Charge	Q_g	V_{DS} = 100 V, V_{GS} = 4.5 V, I_D = 9.6 A		4		nC
Gate-Source Charge	Q_{gs}			1.7		
Gate-Drain Charge	Q_{gd}			1.8		
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 100 V, R_L = 10.55 Ω , I_D = 9.6 A, V_{GEN} = 10 V, R_{GEN} = 6 Ω		10		nS
Rise Time	t_r			8		
Turn-Off Delay Time	$t_{d(off)}$			27		
Fall Time	t_f			13		
Input Capacitance	C_{iss}	V_{DS} = 15 V, V_{GS} = 0 V, f =1 MHz		807		pF
Output Capacitance	C_{oss}			81		
ReverseTransfer Capacitance	C_{rss}			38		

Note:

a. Pulse test: PW <= 300us duty cycle <= 2%.

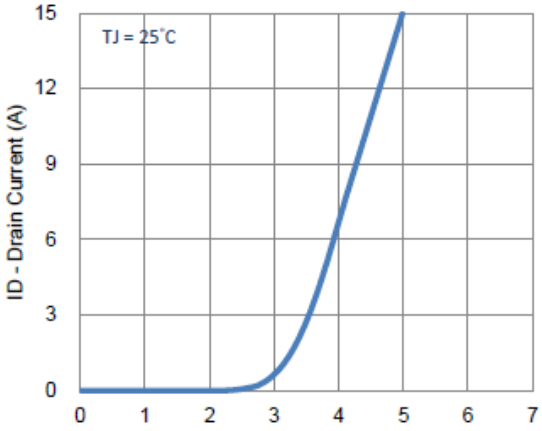
b. Guaranteed by design, not subject to production testing.

Typical Performance Characteristics (N-Channel)



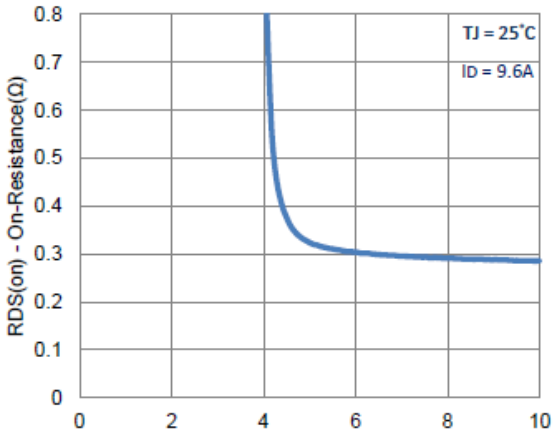
ID-Drain Current (A)

1. On-Resistance vs. Drain Current



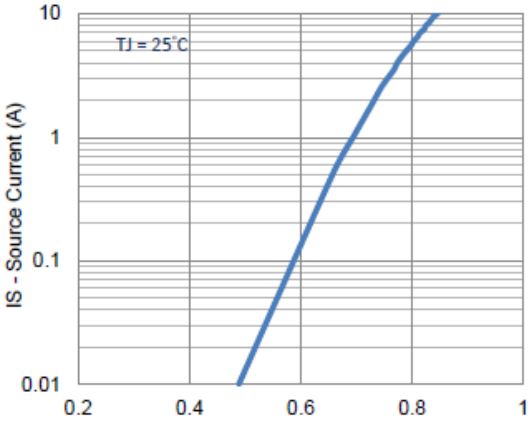
VGS - Gate-to-Source Voltage (V)

2. Transfer Characteristics



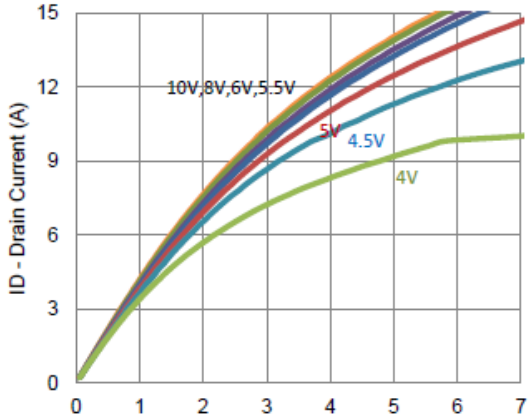
VGS - Gate-to-Source Voltage (V)

3. On-Resistance vs. Gate-to-Source Voltage



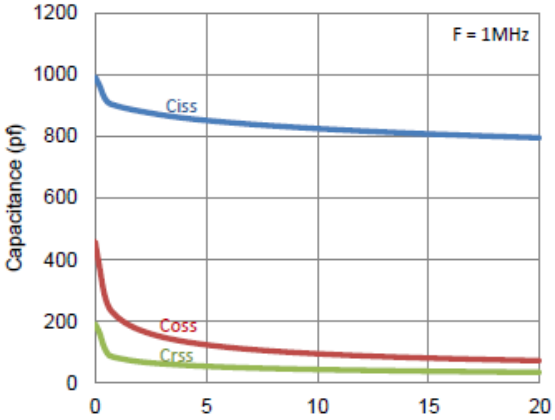
VSD - Source-to-Drain Voltage (V)

4. Drain-to-Source Forward Voltage



VDS - Drain-to-Source Voltage (V)

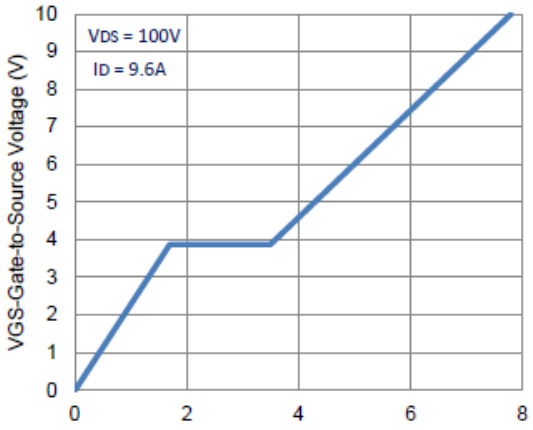
5. Output Characteristics



VDS-Drain-to-Source Voltage (V)

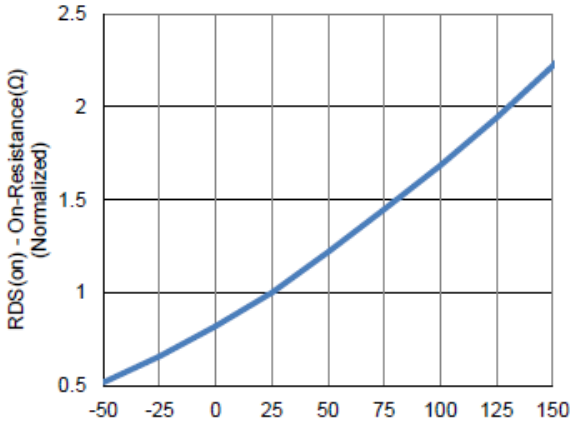
6. Capacitance

Typical Performance Characteristics



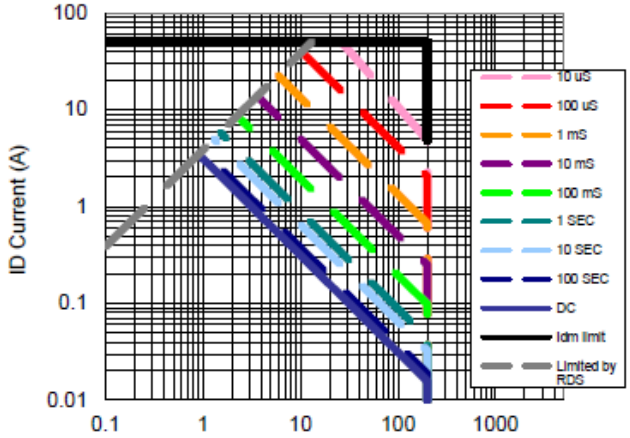
Qg - Total Gate Charge (nC)

7. Gate Charge



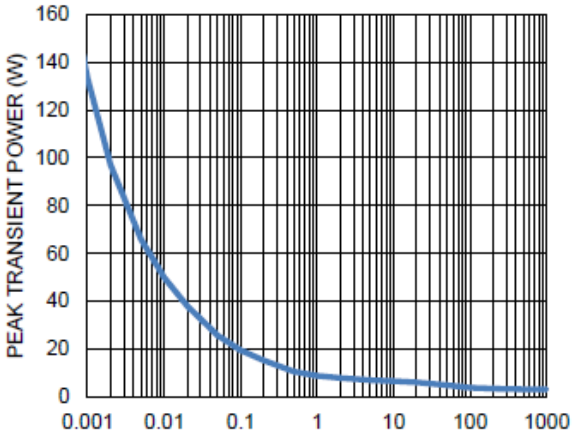
TJ –Junction Temperature(°C)

8. Normalized On-Resistance Vs Junction Temperature



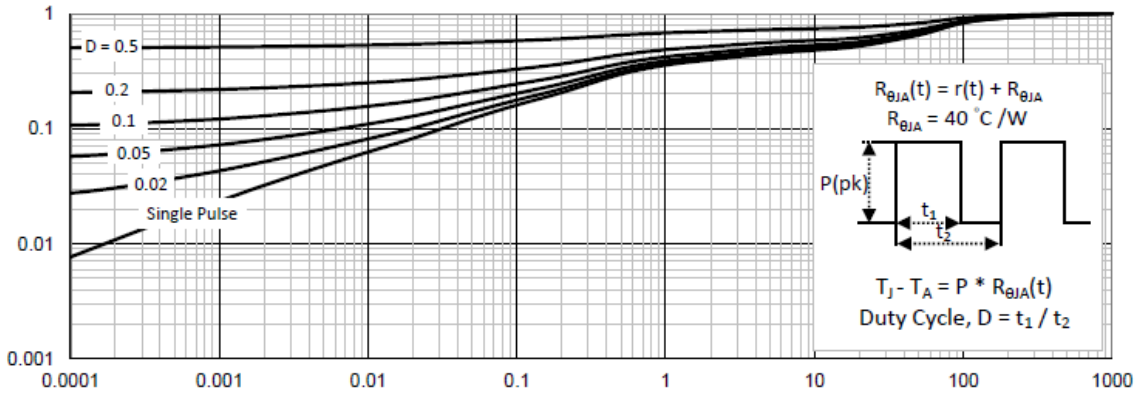
VDS Drain to Source Voltage (V)

9. Safe Operating Area



t1 TIME (SEC)

10. Single Pulse Maximum Power Dissipation

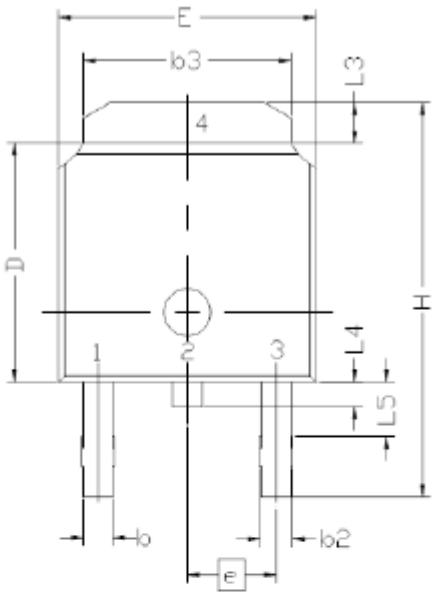


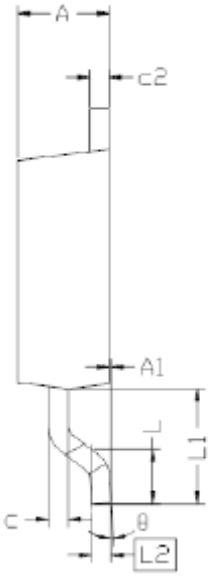
t1 TIME (sec)

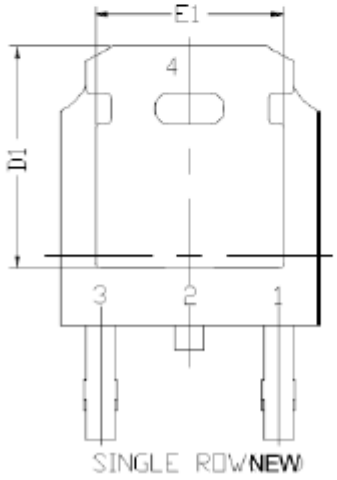
11. Normalized Thermal Transient Junction to Ambient

Packing Information

TO-252







SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
E	6.40	6.60	6.731
L	1.40	1.52	1.77
L1		2.743 REF	
L2		0.508 BSC	
L3	0.89		1.27
L4	0.64		1.01
L5			
D	6.00	6.10	6.223
H	9.40	10.00	10.40
b	0.64	0.76	0.88
b2	0.77	0.84	1.14
b3	5.21	5.34	5.46
e		2.286 BSC	
A	2.20	2.30	2.38
A1	0		0.127
c	0.45	0.50	0.60
c2	0.45	0.50	0.58
D1	5.30		
E1	4.40		
θ	0 ◦		10 ◦

Notes

ACE does not assume any responsibility for use as critical components in life support devices or systems without the express written approval of the president and general counsel of ACE Electronics Co., LTD. As sued herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and shoes failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ACE Technology Co., LTD.
http://www.ace-ele.com/